

TE Internal #: 50935-6

Socket Length 4.27 mm [.168 in], PCB Hole Diameter 1.04 mm [.041

in], Open Bottom, .081 – .162 mm² Wire Size, 28 – 25 AWG Wire

Size, Pin Sockets

View on TE.com >



Connectors > Socket Connectors > Pin Sockets











Socket Length: 4.27 mm [.168 in]

PCB Hole Diameter: 1.04 mm [.041 in]

Socket Sleeve Style: Open Bottom

Wire Size: .081 – .162 mm²

Features

Dimensions

Socket Length	4.27 mm[.168 in]
PCB Hole Diameter	1.04 mm[.041 in]
Wire Size	.081 – .162 mm²
Mating Pin Diameter Range	.33 – .51 mm[.013 – .02 in]
PCB Thickness (Recommended)	.79 – 3.18 mm[.031 – .125 in]

Product Type Features

Socket Sleeve Style	Open Bottom
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Contact Features

Contact Current Rating (Max)	3 A
Contact Spring Plating Material	Gold
Contact Base Material	Beryllium Copper
Contact Mating Area Plating Material Thickness	30 μm[30 μin]



Contact Spring Plating Thickness	.762 μm[30 μin]
Operation/Application	
Circuit Application	Power & Signal
Solder Process Feature	None
Usage Conditions	
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Other	
EU RoHS Compliance	Compliant
EU ELV Compliance	Compliant
Spring Material	Beryllium Copper
Configuration Features	
Compatible With Wire & Cable Type	Discrete Wire
Body Features	
Sleeve Plating Material	Gold Flash over Nickel
Sleeve Material	Copper
Termination Features	
Termination Method to PCB	Through Hole - Press-Fit
Termination Method to Wire & Cable	Solder
Insertion Method	Hand/Semi-Automatic
Packaging Features	
Packaging Method	Loose Piece, Bag
Packaging Quantity	1000

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC



Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per
	homogenous material. Also BFR/CFR/PVC
	Free

Solder Process Capability

Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought











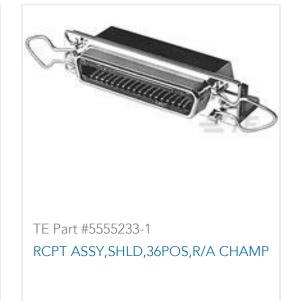












Documents

Product Drawings

SOCKET, MIN-SPR AU-AU SER-1

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_50935-6_Z.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_50935-6_Z.3d_stp.zip

English

Customer View Model

ENG_CVM_CVM_50935-6_Z.2d_dxf.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.